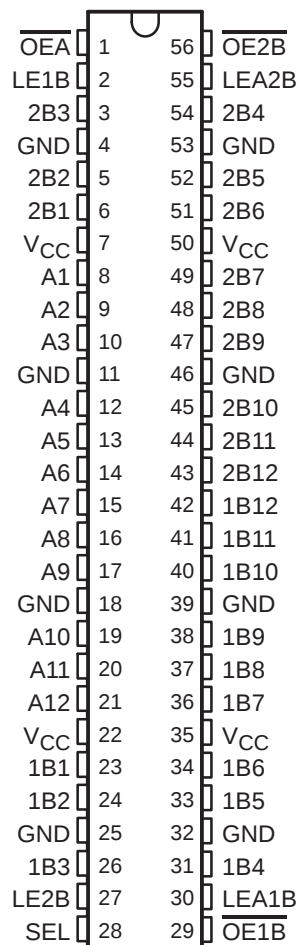


SN54ABTH162260, SN74ABTH162260 12-BIT TO 24-BIT MULTIPLEXED D-TYPE LATCHES WITH SERIES-DAMPING RESISTORS AND 3-STATE OUTPUTS

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- Members of the Texas Instruments *Widebus™* Family
- B-Port Outputs Have Equivalent 25-Ω Series Resistors, So No External Resistors Are Required
- State-of-the-Art *EPIC-II B™* BiCMOS Design Significantly Reduces Power Dissipation
- ESD Protection Exceeds 2000 V Per MIL-STD-883, Method 3015; Exceeds 200 V Using Machine Model (C = 200 pF, R = 0)
- Latch-Up Performance Exceeds 500 mA Per JEDEC Standard JESD-17
- Typical V_{OLP} (Output Ground Bounce) < 1 V at $V_{CC} = 5$ V, $T_A = 25^\circ\text{C}$
- High-Impedance State During Power Up and Power Down
- Distributed V_{CC} and GND Pin Configuration Minimizes High-Speed Switching Noise
- Flow-Through Architecture Optimizes PCB Layout
- Bus Hold on Data Inputs Eliminates the Need for External Pullup/Pulldown Resistors
- Package Options Include Plastic 300-mil Shrink Small-Outline (DL) Package and 380-mil Fine-Pitch Ceramic Flat (WD) Package Using 25-mil Center-to-Center Spacings

SN54ABTH162260 . . . WD PACKAGE
SN74ABTH162260 . . . DL PACKAGE
(TOP VIEW)



description

The 'ABTH162260 are 12-bit to 24-bit multiplexed D-type latches used in applications where two separate data paths must be multiplexed onto, or demultiplexed from, a single data path. Typical applications include multiplexing and/or demultiplexing of address and data information in microprocessor or bus-interface applications. These devices are also useful in memory-interleaving applications.

Three 12-bit I/O ports (A1–A12, 1B1–1B12, and 2B1–2B12) are available for address and/or data transfer. The output-enable ($\overline{OE1B}$, $\overline{OE2B}$, and $\overline{OEA}$) inputs control the bus-transceiver functions. The $\overline{OE1B}$ and $\overline{OE2B}$ control signals also allow bank control in the A-to-B direction.

Address and/or data information can be stored using the internal storage latches. The latch-enable (LE1B, LE2B, LEA1B, and LEA2B) inputs are used to control data storage. When the latch-enable input is high, the latch is transparent. When the latch-enable input goes low, the data present at the inputs is latched and remains latched until the latch-enable input is returned high.

The B-port outputs, which are designed to sink up to 12 mA, include equivalent 25-Ω series resistors to reduce overshoot and undershoot.



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**TEXAS
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SN54ABTH162260, SN74ABTH162260

12-BIT TO 24-BIT MULTIPLEXED D-TYPE LATCHES

WITH SERIES-DAMPING RESISTORS AND 3-STATE OUTPUTS

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description (continued)

Active bus-hold circuitry is provided to hold unused or floating data inputs at a valid logic level.

When V_{CC} is between 0 and 2.1 V, the device is in the high-impedance state during power up or power down. However, to ensure the high-impedance state above 2.1 V, $\overline{OE}$ should be tied to V_{CC} through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

The SN54ABTH162260 is characterized for operation over the full military temperature range of -55°C to 125°C . The SN74ABTH162260 is characterized for operation from -40°C to 85°C .

Function Tables

B TO A ($\overline{OEB} = \text{H}$)

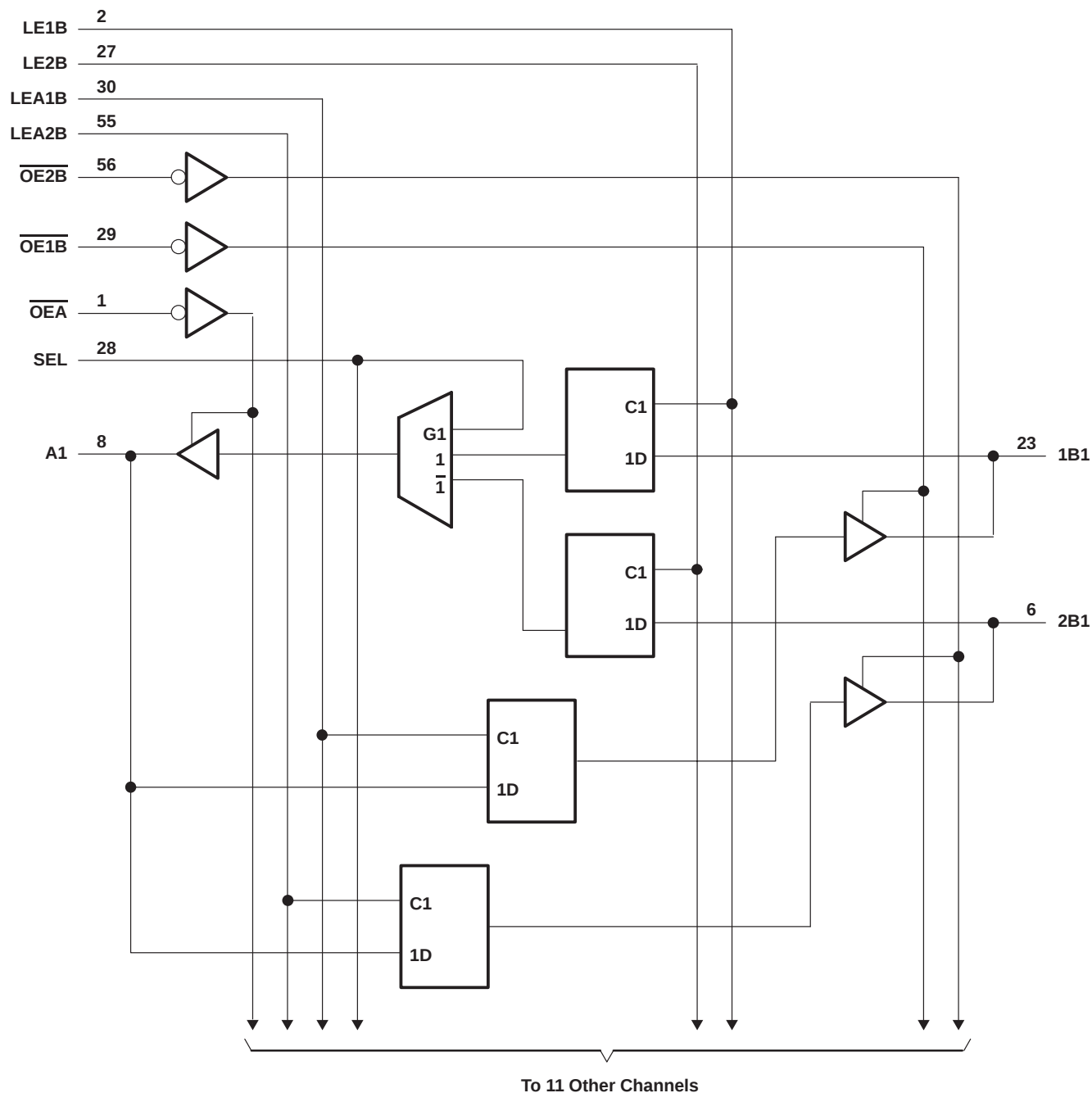
INPUTS						OUTPUT A
1B	2B	SEL	LE1B	LE2B	$\overline{OEA}$	
H	X	H	H	X	L	H
L	X	H	H	X	L	L
X	X	H	L	X	L	A ₀
X	H	L	X	H	L	H
X	L	L	X	H	L	L
X	X	L	X	L	L	A ₀
X	X	X	X	X	H	Z

A TO B ($\overline{OEA} = \text{H}$)

INPUTS					OUTPUTS	
A	LEA1B	LEA2B	$\overline{OE1B}$	$\overline{OE2B}$	1B	2B
H	H	H	L	L	H	H
L	H	H	L	L	L	L
H	H	L	L	L	H	2B ₀
L	H	L	L	L	L	2B ₀
H	L	H	L	L	1B ₀	H
L	L	H	L	L	1B ₀	L
X	L	L	L	L	1B ₀	2B ₀
X	X	X	H	H	Z	Z
X	X	X	L	H	Active	Z
X	X	X	H	L	Z	Active
X	X	X	L	L	Active	Active

SN54ABTH162260, SN74ABTH162260
12-BIT TO 24-BIT MULTIPLEXED D-TYPE LATCHES
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logic diagram (positive logic)



SN54ABTH162260, SN74ABTH162260

12-BIT TO 24-BIT MULTIPLEXED D-TYPE LATCHES

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absolute maximum ratings over operating free-air temperature range (unless otherwise noted)[†]

Supply voltage range, V_{CC}	–0.5 V to 7 V
Input voltage range, V_I (see Note 1)	–0.5 V to 7 V
Voltage range applied to any output in the high or power-off state, V_O	–0.5 V to 5.5 V
Current into any output in the low state, I_O : SN54ABTH162260 (A port)	96 mA
SN74ABTH162260 (A port)	128 mA
B port	30 mA
Input clamp current, I_{IK} ($V_I < 0$)	–18 mA
Output clamp current, I_{OK} ($V_O < 0$)	–50 mA
Package thermal impedance, θ_{JA} (see Note 2): DL package	74°C/W
Storage temperature range, T_{stg}	–65°C to 150°C

[†] Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.
2. The package thermal impedance is calculated in accordance with EIA/JEDEC Std JESD51.

recommended operating conditions (see Note 3)

		SN54ABTH162260		SN74ABTH162260		UNIT
		MIN	MAX	MIN	MAX	
V_{CC}	Supply voltage	4.5	5.5	4.5	5.5	V
V_{IH}	High-level input voltage	2		2		V
V_{IL}	Low-level input voltage		0.8		0.8	V
V_I	Input voltage	0	V_{CC}	0	V_{CC}	V
I_{OH}	High-level output current		–24		–32	mA
I_{OL}	Low-level output current		A port		48	mA
			B port		12	
$\Delta t/\Delta v$	Input transition rise or fall rate		Outputs enabled		10	ns/V
$\Delta t/\Delta V_{CC}$	Power-up ramp rate	200		200		μs/V
T_A	Operating free-air temperature	–55	125	–40	85	°C

NOTE 3: Unused control inputs must be held high or low to prevent them from floating.

SN54ABTH162260, SN74ABTH162260
12-BIT TO 24-BIT MULTIPLEXED D-TYPE LATCHES
WITH SERIES-DAMPING RESISTORS AND 3-STATE OUTPUTS

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electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER		TEST CONDITIONS		T _A = 25°C			SN54ABTH162260		SN74ABTH162260		UNIT
				MIN	TYP†	MAX	MIN	MAX	MIN	MAX	
V _{IK}		V _{CC} = 4.5 V, I _I = –18 mA				–1.2		–1.2		–1.2	V
V _{OH}		V _{CC} = 4.5 V, I _{OH} = –3 mA		2.5			2.5		2.5		V
		V _{CC} = 5 V, I _{OH} = –3 mA		3			3		3		
		V _{CC} = 4.5 V	I _{OH} = –24 mA	2			2				
			I _{OH} = –32 mA	2*					2		
V _{OL}	A port	V _{CC} = 4.5 V	I _{OL} = 48 mA			0.55		0.55			V
			I _{OL} = 64 mA			0.55*			0.55		
	B port		I _{OL} = 12 mA			0.8		0.8		0.8	
V _{hys}					100						mV
I _I	Control inputs	V _{CC} = 0 to 5.5 V, V _I = V _{CC} or GND				±1		±1		±1	μA
	A or B ports	V _{CC} = 2.1 V to 5.5 V, V _I = V _{CC} or GND				±20		±20		±20	
I _I (hold)	A or B ports	V _{CC} = 4.5 V	V _I = 0.8 V						100		μA
			V _I = 2 V						–100		
I _{OZPU} ‡		V _{CC} = 0 to 2.1 V, V _O = 0.5 V to 2.7 V, $\overline{OE}$ = X				±50		±50		±50	μA
I _{OZPD} ‡		V _{CC} = 2.1 V to 0, V _O = 0.5 V to 2.7 V, $\overline{OE}$ = X				±50		±50		±50	μA
I _{OZH} §		V _{CC} = 2.1 V to 5.5 V, V _O = 2.7 V, $\overline{OE}$ ≥ 2 V				10		10		10	μA
I _{OZL} §		V _{CC} = 2.1 V to 5.5 V, V _O = 0.5 V, $\overline{OE}$ ≥ 2 V				–10		–10		–10	μA
I _{off}		V _{CC} = 0, V _I or V _O ≤ 4.5 V				±100				±100	μA
I _{CEX}	Outputs high	V _{CC} = 5.5 V, V _O = 5.5 V				50		50		50	μA
I _O ¶		V _{CC} = 5.5 V, V _O = 2.5 V		–50	–100	–225	–50	–225	–50	–225	mA
I _{CC}	Outputs high	V _{CC} = 5.5 V, I _O = 0, V _I = V _{CC} or GND				1.5		1.5		1.5	mA
	Outputs low					63		63		63	
	Outputs disabled					1		1		1	
ΔI _{CC} #		V _{CC} = 5.5 V, One input at 3.4 V, Other inputs at V _{CC} or GND				1		1.5		1	mA
C _i		V _I = 2.5 V or 0.5 V				3					pF
C _O		V _O = 2.5 V or 0.5 V				11.5					pF

* On products compliant to MIL-PRF-38535, this parameter does not apply.

† All typical values are at V_{CC} = 5 V.

‡ This parameter is characterized but not tested.

§ The parameters I_{OZH} and I_{OZL} include the input leakage current.

¶ Not more than one output should be tested at a time, and the duration of the test should not exceed one second.

This is the increase in supply current for each input that is at the specified TTL voltage level rather than V_{CC} or GND.

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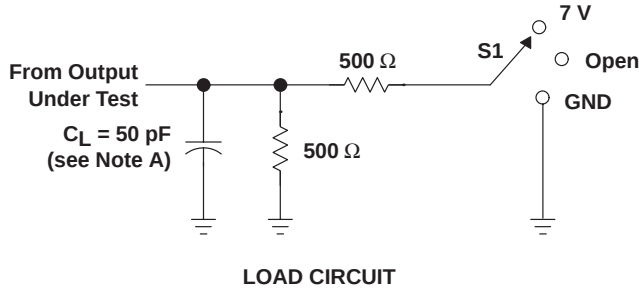
timing requirements over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted) (see Figure 1)

		V _{CC} = 5 V, T _A = 25°C		SN54ABTH162260		SN74ABTH162260		UNIT
		MIN	MAX	MIN	MAX	MIN	MAX	
t _w	Pulse duration, LE1B, LE2B, LEA1B, or LEA2B high	3.3		3.3		3.3		ns
t _{su}	Setup time, data before LE1B, LE2B, LEA1B, or LEA2B↓	1.5		1.5		1.5		ns
t _h	Hold time, data after LE1B, LE2B, LEA1B, or LEA2B↓	1		1		1		ns

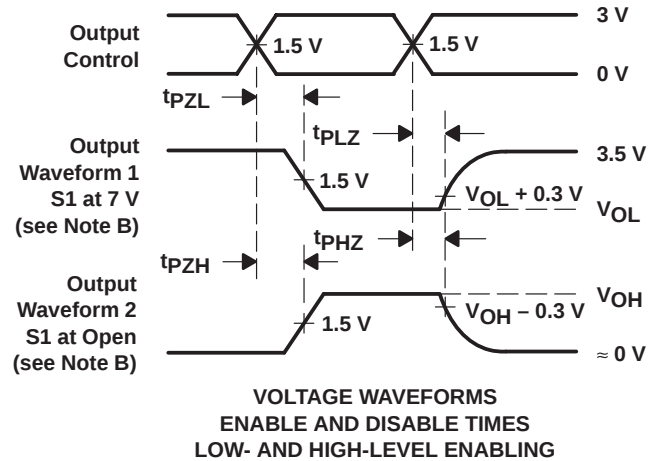
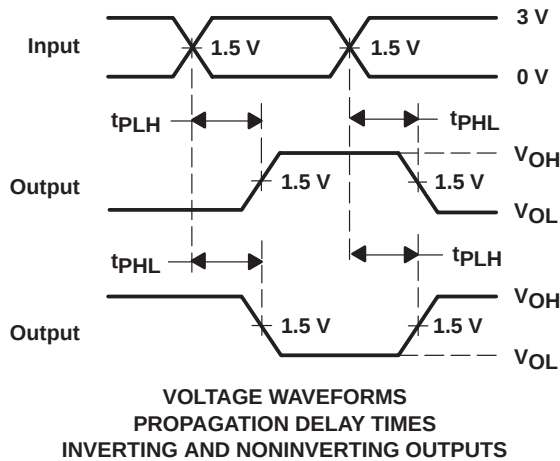
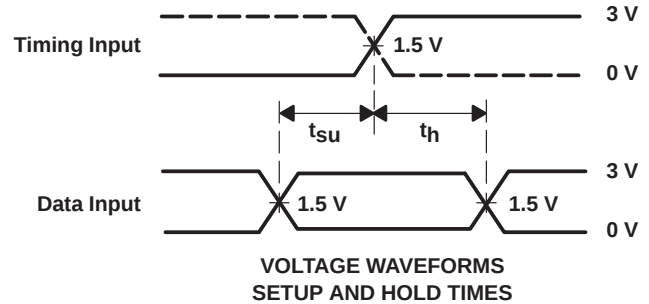
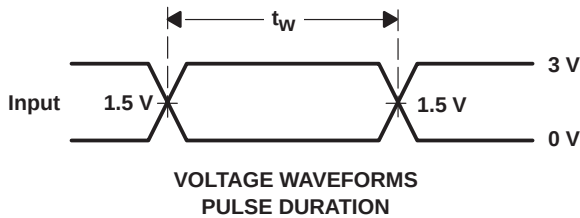
switching characteristics over recommended ranges of supply voltage and operating free-air temperature, C_L = 50 pF (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	V _{CC} = 5 V, T _A = 25°C			SN54ABTH162260		SN74ABTH162260		UNIT
			MIN	TYP	MAX	MIN	MAX	MIN	MAX	
t _{PLH}	A	B	1.4	3.6	5.2	1.4	6.3	1.4	6.1	ns
t _{PHL}			2.7	4.8	6.4	2.7	7.4	2.7	7.1	
t _{PLH}	B	A	1.6	3.6	5.2	1.6	6.4	1.6	6	ns
t _{PHL}			1.7	3.8	5.5	1.7	6.5	1.7	6.2	
t _{PLH}	LE	A	1.8	3.9	5.3	1.8	6.6	1.8	6.3	ns
t _{PHL}			2.3	4.1	5.4	2.3	6.1	2.3	5.8	
t _{PLH}	LE	B	1.6	3.7	5.4	1.6	6.4	1.6	6.1	ns
t _{PHL}			2.8	4.9	6.4	2.8	7.5	2.8	7.1	
t _{PLH}	SEL (1B)	A	1.5	3.6	5	1.5	5.9	1.5	5.6	ns
t _{PHL}			1.8	3.5	4.8	1.8	5.2	1.8	5	
t _{PLH}	SEL (2B)	A	1.2	3.6	5.1	1.2	6.5	1.2	6.3	ns
t _{PHL}			1.7	4	5.5	1.7	6.5	1.7	6.2	
t _{PZH}	$\overline{\text{OE}}$	A	1.1	3.5	5.2	1.1	6.5	1.1	6.3	ns
t _{PZL}			2.1	4.2	5.7	2.1	6.6	2.1	6.5	
t _{PZH}	$\overline{\text{OE}}$	B	1	3.4	4.9	1	6.4	1	6.3	ns
t _{PZL}			2.9	5.5	6.8	2.9	8.3	2.9	8.2	
t _{PHZ}	$\overline{\text{OE}}$	A	2.5	4.5	5.9	2.5	6.9	2.5	6.7	ns
t _{PLZ}			1.8	3.4	4.8	1.8	5.6	1.8	5.2	
t _{PHZ}	$\overline{\text{OE}}$	B	2.1	4.4	5.7	2.1	7.7	2.1	7.5	ns
t _{PLZ}			1.7	3.9	5.4	1.7	6.3	1.7	6.2	

PARAMETER MEASUREMENT INFORMATION



TEST	S1
t_{PLH}/t_{PHL}	Open
t_{PLZ}/t_{PZL}	7 V
t_{PHZ}/t_{PZH}	Open



- NOTES: A. C_L includes probe and jig capacitance.
B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
C. All input pulses are supplied by generators having the following characteristics: $PRR \leq 10 \text{ MHz}$, $Z_O = 50 \Omega$, $t_r \leq 2.5 \text{ ns}$, $t_f \leq 2.5 \text{ ns}$.
D. The outputs are measured one at a time with one transition per measurement.

Figure 1. Load Circuit and Voltage Waveforms

PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
74ABTH162260DLG4	ACTIVE	SSOP	DL	56	20	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
74ABTH162260DLRG4	ACTIVE	SSOP	DL	56	1000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ABTH162260DL	ACTIVE	SSOP	DL	56	20	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ABTH162260DLR	ACTIVE	SSOP	DL	56	1000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

⁽²⁾ Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

⁽³⁾ MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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TAPE AND REEL INFORMATION



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74ABTH162260DLR	SSOP	DL	56	1000	330.0	32.4	11.35	18.67	3.1	16.0	32.0	Q1

TAPE AND REEL BOX DIMENSIONS



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74ABTH162260DLR	SSOP	DL	56	1000	346.0	346.0	49.0

DL (R-PDSO-G**)

PLASTIC SMALL-OUTLINE PACKAGE

48 PINS SHOWN



- NOTES: A. All linear dimensions are in inches (millimeters).
 B. This drawing is subject to change without notice.
 C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).
 D. Falls within JEDEC MO-118

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